

## **3mm RIGHT ANGLE LED INDICATOR**

Part Number: WP42WUM/GYW

Green Yellow

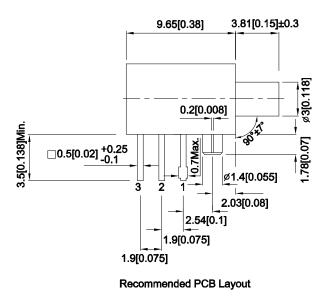
### **Features**

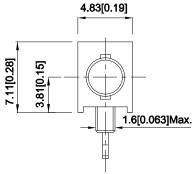
- Pre-trimmed leads for pc mounting.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability-life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

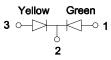
## **Descriptions**

- The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.
- The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

## **Package Dimensions**







- 1 Anode Green
- 2 Common Cathode
- 3 Anode Yellow

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.

Ø0.889x3

1.9[0.075]

Lead spacing is measured where the leads emerge from the package.
 The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

1.9[0.075] 2.54[0.1]

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ø1.7[0.067]



## **Selection Guide**

Part No.	Emitting Color (Material)	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		<i>,</i> .	Min.	Тур.	201/2
WP42WUM/GYW	Green (GaP)	White Diffused	4	10	100°
VVF42VVOIW//GTVV	Yellow (GaAsP/GaP)	Willie Dillused	2	6	

- 1. 01 / 2 is the angle from optical centerline where the luminous intensity is 1 / 2 of the optical peak value.

  2. Luminous intensity / luminous Flux: + / -15%.
- 3. Luminous intensity value is traceable to CIE127-2007 standards.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green Yellow	565 590		nm	IF=20mA
λD [1]	Dominant Wavelength	Green Yellow	568 588		nm	Ir=20mA
Δλ1/2	Spectral Line Half-width	Green Yellow	30 35		nm	IF=20mA
С	Capacitance	Green Yellow	15 20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green Yellow	2.2 2.1	2.5 2.5	V	IF=20mA
lR	Reverse Current	Green Yellow		10 10	uA	V <sub>R</sub> = 5V

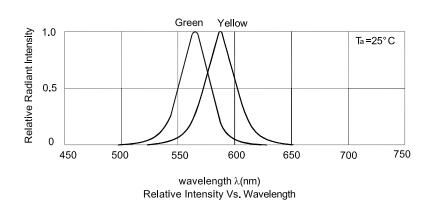
- 1. Wavelength: + / -1nm.
  2. Forward Voltage: + / -0.1V.
  3. Wavelength value is traceable to CIE127-2007 standards.
- 4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or

### Absolute Maximum Ratings at TA=25°C

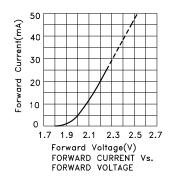
Parameter	Green	Yellow	Units		
Power dissipation	62.5	75	mW		
DC Forward Current	25	30	mA		
Peak Forward Current [1]	140	140	mA		
Reverse Voltage		V			
Operating / Storage Temperature	-40°C To +85°C				
Lead Solder Temperature [2]	260°C For 3 Seconds				
Lead Solder Temperature [3]	260°C For 5 Seconds				

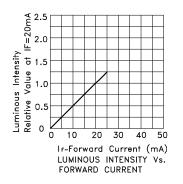
- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
- 2. 2mm below package base.
- 5. Smm below package base.
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   Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity - Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

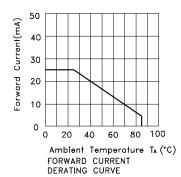
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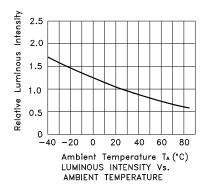


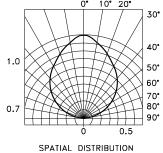
## WP42WUM/GYW Green





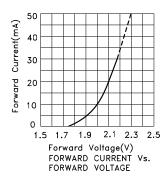


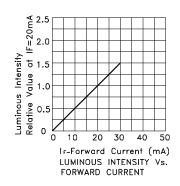


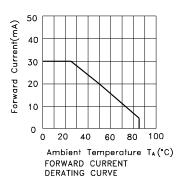


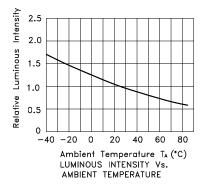
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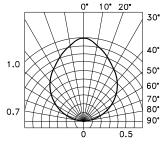
## Yellow





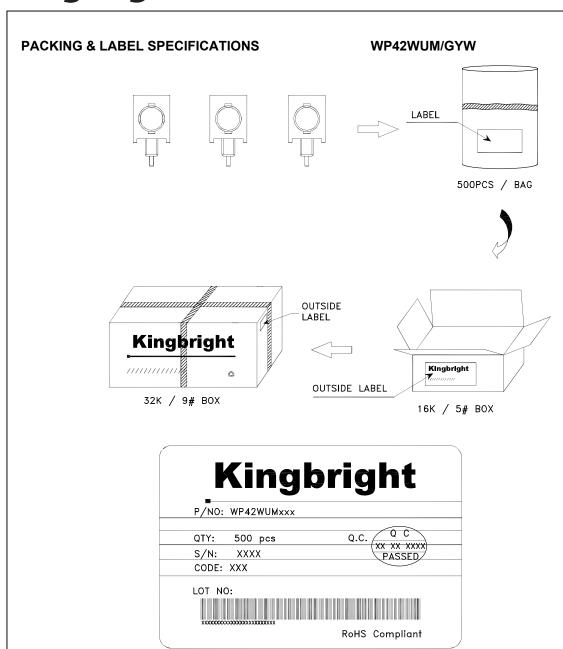






SPATIAL DISTRIBUTION

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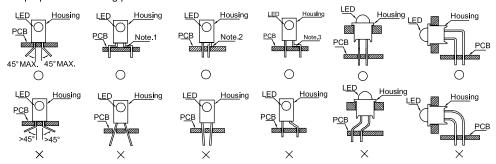
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### **PRECAUTIONS**

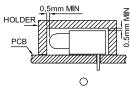
- 1. Storage conditions:
  - a. Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
  - b.LEDs should be stored with temperature ≤ 30°C and relative humidity < 60%.
  - c.Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85  $\sim$  100°C.
- The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

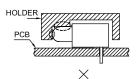


"  $\bigcirc$  " Correct mounting method " imes " Incorrect mounting method

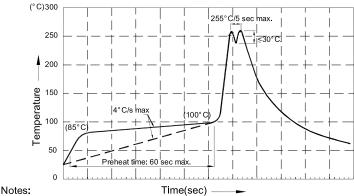
Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

3. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.





- 4. The tip of the soldering iron should never touch the lens epoxy.
- 5. Through-hole LEDs are incompatible with reflow soldering.
- If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 7. Recommended Wave Soldering Profiles:



- 1.Recommend pre-heat temperature of 105° C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260° C
- 2.Peak wave soldering temperature between 245° C ~ 255° C for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4 Fixtures should not incur stress on the component when mounting and during soldering process.
- 5.SAC 305 solder alloy is recommended.
- 6.No more than one wave soldering pass.

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